

# AO3401

## -30V P-Channel Enhancement Mode MOSFET

$V_{DS} = -30V$

$R_{DS(ON)}, V_{GS} @ -10V, I_{DS} @ -4.2A < 64m\ \Omega$

$R_{DS(ON)}, V_{GS} @ -4.5V, I_{DS} @ -4.0A < 75m\ \Omega$

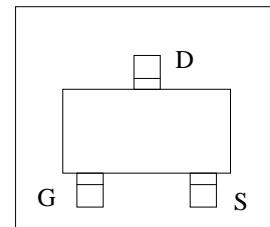
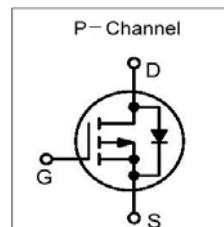
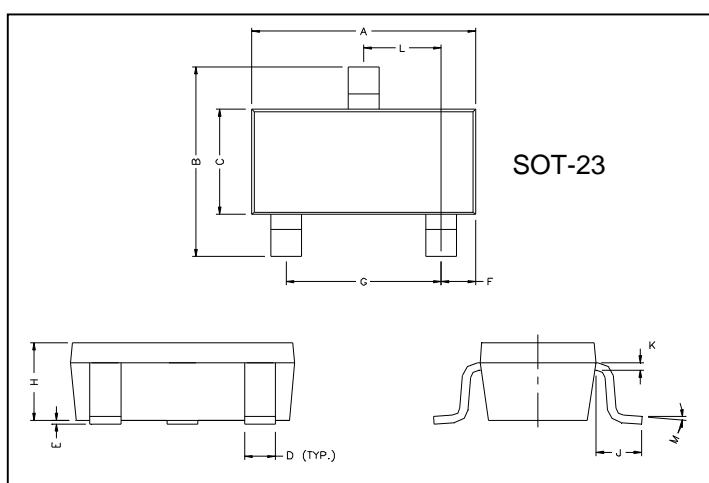
$R_{DS(ON)}, V_{GS} @ -2.5V, I_{DS} @ -1.0A < 120m\ \Omega$

### Features

Advanced trench process technology

High Density Cell Design For Ultra Low On-Resistance

### Package Dimensions



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.80	3.00	G	1.80	2.00
B	2.30	2.50	H	0.90	1.1
C	1.20	1.40	K	0.10	0.20
D	0.30	0.50	J	0.35	0.70
E	0	0.10	L	0.92	0.98
F	0.45	0.55	M	0°	10°

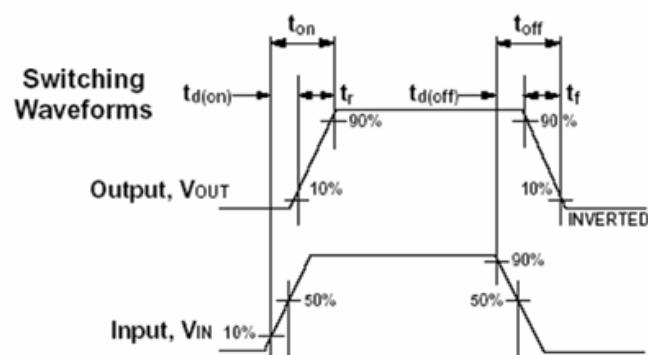
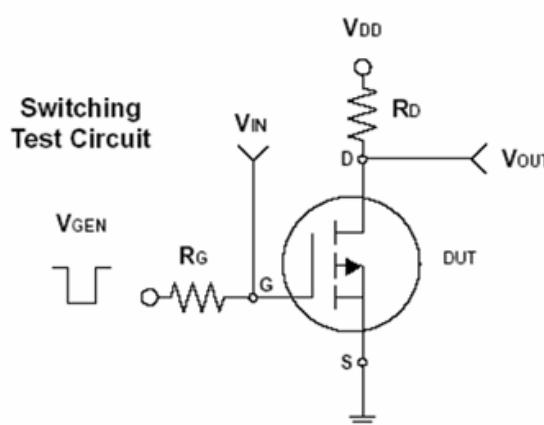
### Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	12	
Continuous Drain Current	$I_D$	-4.2	A
Pulsed Drain Current	$I_{DM}$	-30	
Maximum Power Dissipation	$P_D$	1.4	W
		1	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150	°C
Junction-to-Ambient Thermal Resistance (PCB mounted)	$R_{\theta JA}$	125	°C/W

## ELECTRICAL CHARACTERISTICS (TA = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Miax.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-30			V
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -4.2A		42.0	64.0	mΩ
Drain-Source On-State Resistance	R <sub>DS(on)</sub>			64.0	75.0	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>			80.0	120.0	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.7	-1	-1.3	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -24V, V <sub>GS</sub> = 0V			-1	uA
Gate Body Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 12V, V <sub>DS</sub> = 0V			± 100	nA
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -5A	7	11	—	S
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 20V, I <sub>D</sub> = 5.7A V <sub>GS</sub> = 10V		9.4		nC
Gate-Source Charge	Q <sub>gs</sub>			2		
Gate-Drain Charge	Q <sub>gd</sub>			3		
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 20V, RL=20Ω I <sub>D</sub> = 1A, V <sub>GEN</sub> = 10V R <sub>G</sub> = 6Ω		6.3		ns
Turn-On Rise Time	t <sub>r</sub>			3.2		
Turn-Off Delay Time	t <sub>d(off)</sub>			38.2		
Turn-Off Fall Time	t <sub>f</sub>			12		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 8V, V <sub>GS</sub> = 0V f = 1.0 MHz		954		pF
Output Capacitance	C <sub>oss</sub>			115		
Reverse Transfer Capacitance	C <sub>rss</sub>			77		
<b>Source-Drain Diode</b>						
Max. Diode Forward Current	I <sub>s</sub>				-2.2	A
Diode Forward Voltage	V <sub>SD</sub>	I <sub>s</sub> = 1.8A, V <sub>GS</sub> = 0V			-1.0	V

Note: Pulse test: pulse width <= 300us, duty cycle<= 2%



Typical Characteristics ( $T_J = 25^\circ\text{C}$  Noted)